



TETRA Designed Spacer Pill II

TDSP DISPLACEMENT SYSTEM

Overview

TETRA Designed Spacer Pill (TDSP II) spacer is a specially formulated chemical wash blended with various surfactants and solvents in fresh water or saline solution.

This is the second stage of the TETRA Technologies TDSP multi-stage weighted spacer system. This spacer is designed to be in turbulent flow to attract, disperse, and remove residual mud left on tubulars after the bulk of the mud has been displaced by TDSP I spacer. This spacer does not eliminate the need for proper mud conditioning or casing scraper runs prior to displacement.

Features and Benefits

- Preformulated to save mixing time and rig cost
- Eliminates need for multiple products in inventory at rig site
- Saves rig time
- Eliminates human error since mixing is performed at plant by knowledgeable personnel instead of rig site
- Custom formulated for optimal performance

Applicable Information

TDSP II spacer is specially blended at a TETRA service facility thereby eliminating rig-site mixing. TDSP II spacer volumes and density requirements are directly related to wellbore geometry, temperature, pressure, mud rheology and mud density.

Safety and Handling

Avoid skin and eye contact, inhalation or ingestion. For skin contact, wash with soap and large quantities of water. For eye contact, flush with large quantities of water. Use properly designed respirator if adequate ventilation is not available. Refer to the Safety Data Sheet for specific details.

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